

WIZ811MJ Partlist

Item	Q.ty	Reference	Part	Tech. Characteristics	Package
1	2	C1,C2	18pF	50V-20% Ceramic	CASE 0603
2	11	C3,C4,C5,C6,C10,C12,C13, C14,C15,C16,C17	0.1uF	50V-20% Ceramic	CASE 0603
3	2	C7,C11	4.7uF/16V	16Vmin 10%	EIA/IECQ 3216
4	1	C8	1uF/16V	16Vmin 10%	EIA/IECQ 3216
5	1	C9	0.01uF	50V-20% Ceramic	CASE 0603
6	2	FB2,FB1	1uH Chip Ferrite Inductor	1uH, 50mA	CASE 0805
7	2	J1,J2	2X10 20PIN 2.54mm DIP STRAIGHT Header	2 X 10 2.54mm pitch	
8	1	R1	1M	1/10W-5% SMD	CASE 0603
9	4	R2,R3,R8,R9	51 1%	1/10W-1% SMD	CASE 0603
10	2	R4,R5	200	1/10W-5% SMD	CASE 0603
11	1	R6	12K (1%)	1/10W-1% SMD	CASE 0603
12	1	R7	300 (1%)	1/10W-1% SMD	CASE 0603
13	1	R11	4.7K	1/10W-5% SMD	CASE 0603
14	1	U1	W5100	WIZnet Hardware TCP/IP	LQFP80
15	1	U2	RJ113BZ	Transformer + RJ45	
16	1	U4	74AHC1G04GW	Inverting Buffer (vendor : NXP)	TSSOP5
17	1	Y1	25MHz (SMD)	SMD Type, CL=18pF	SX-1
18	1		WIZ811MJ REV1.0 1.6T 4LAYER	PRINTED CIRCUIT BOARD	